## INTEGRATED CIRCUITS

## DATA SHEET

# **74F132**Quad 2-input NAND Schmitt trigger

Product specification

1991 Jun 26

IC15 Data Handbook



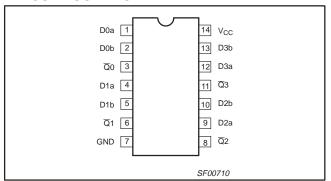


74F132

#### **DESCRIPTION**

The 74F132 contains four 2-input NAND gates which accept standard TTL input signals and provide standard TTL output levels. They are capable of transforming slowly changing input signals into sharply defined, jitter-free output signals. In addition, they have greater noise margin than conventional NAND gates. Each circuit contains a 2-input Schmitt trigger followed by a Darlington level shifter and a phase splitter driving a TTL totem-pole output. The Scmitt trigger uses positive feedback to effectively speed-up slow input transitions and provide different input threshold voltages for positive and negative-going transitions. This hysteresis between the positive-going and negative-going input threshold (typically 800mV) is determined by resistor ratios and is essentially insensitive to temperature and supply voltage variations. As long as three inputs remain at a more positive voltage than  $V_{\mathsf{T+MAX}}$ , the gate will respond in the transition of the other input as shown in Waveform 1.

#### **PIN CONFIGURATION**



TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F132	6.3ns	13mA

## **ORDERING INFORMATION**

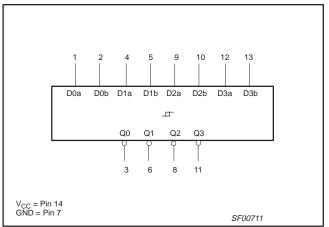
DESCRIPTION	COMMERCIAL RANGE $V_{CC}$ = 5V $\pm 10\%$ , $T_{amb}$ = 0°C to +70°C	PKG DWG #		
14-pin plastic DIP	N74F132N	SOT27-1		
14-pin plastic SO	N74F132D	SOT108-1		

## INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

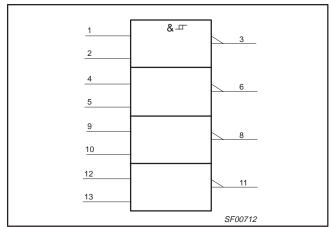
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW		
Dna, Dnb	Data inputs	1.0/1.0	20μA/0.6mA		
Qn	Data output	50/33	1.0mA/20mA		

NOTE: One (1.0) FAST unit load is defined as: 20µA in the High state and 0.6mA in the Low state.

## **LOGIC SYMBOL**



## **IEC/IEEE SYMBOL**

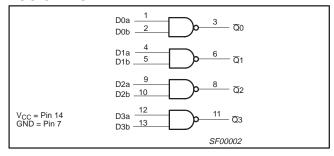


Philips Semiconductors Product specification

## Quad 2-input NAND Schmitt trigger

74F132

## **LOGIC DIAGRAM**



## **FUNCTION TABLE**

INP	UTS	OUTPUT
Dna	Dnb	Qn
L	L	Н
L	Н	Н
Н	L	Н
Н	Н	L

## NOTES:

H = High voltage level L = Low voltage level

## **ABSOLUTE MAXIMUM RATINGS**

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V <sub>CC</sub>	Supply voltage	−0.5 to +7.0	V
V <sub>IN</sub>	Input voltage	-0.5 to +7.0	V
I <sub>IN</sub>	Input current	−30 to +5	mA
V <sub>OUT</sub>	Voltage applied to output in High output state	–0.5 to V <sub>CC</sub>	V
I <sub>OUT</sub>	Current applied to output in Low output state	40	mA
T <sub>amb</sub>	Operating free-air temperature range	0 to +70	°C
T <sub>stg</sub>	Storage temperature	-65 to +150	°C

## RECOMMENDED OPERATING CONDITIONS

SYMBOL	DADAMETER		LINUT		
STWIBUL	PARAMETER	MIN	NOM	MAX	UNIT
V <sub>CC</sub>	Supply voltage	4.5	5.0	5.5	V
I <sub>IK</sub>	Input clamp current			-18	mA
I <sub>OH</sub>	High-level output current			-1	mA
I <sub>OL</sub>	Low-level output current			20	mA
T <sub>amb</sub>	Operating free-air temperature range	0		+70	°C

1991 Jun 26 3

Philips Semiconductors Product specification

## Quad 2-input NAND Schmitt trigger

74F132

#### DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

OVMDOL	DADAMETED		TEOT CONDITIO	NO1		LIMITS		LINUT	
SYMBOL	PARAMETER		TEST CONDITION	ons'	MIN	TYP <sup>2</sup>	MAX	UNIT	
V <sub>T+</sub>	Positive-going threshold		V <sub>CC</sub> = 5.0V		1.5	1.7	2.0	V	
V <sub>T</sub>	Negative-going threshold-		V <sub>CC</sub> = 5.0V		0.7	0.9	1.1	V	
$\Delta V_{T}$	Hysteresis (V <sub>T+</sub> – V <sub>T-</sub> )		V <sub>CC</sub> = 5.0V		0.4	0.8		V	
V	Lligh level output voltage		$V_{CC} = MIN,$	±10%V <sub>CC</sub>	2.5			V	
V <sub>OH</sub>	High-level output voltage		$V_{I=}V_{T-MAX}$ , $I_{OH} = MAX$	2.7	3.4		V		
V	Levy level entruit velte ee		$V_{CC} = MIN,$	±10%V <sub>CC</sub>		0.30	0.50	V	
V <sub>OL</sub>	Low-level output voltage		$V_{I=}V_{T+MAX}$ , $I_{OL} = MAX$	±5%V <sub>CC</sub>		0.30	0.50	V	
V <sub>IK</sub>	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$		-0.73	-1.2	V		
I <sub>T+</sub>	Input current at positive-going thresh	nold	$V_{CC} = 5.0V, V_{I} = V_{T+}$		0		μΑ		
I <sub>T</sub> _	Input current at negative-going thres	shold	$V_{CC} = 5.0V, V_{I} = V_{T-}$		-350		μΑ		
I <sub>I</sub>	Input current at maximum input volta	age	$V_{CC} = MAX, V_I = 7.0V$			100	μΑ		
I <sub>IH</sub>	High-level input current		$V_{CC} = MAX, V_I = 2.7V$			20	μΑ		
I <sub>IL</sub>	Low-level input current		$V_{CC} = MAX, V_I = 0.5V$			-0.6	mA		
los	Short-circuit output current <sup>3</sup>		V <sub>CC</sub> = MAX		-60		-150	mA	
	Cumply oursent (total)	I <sub>CCH</sub>	V MAY	V <sub>I N</sub> = GND		8.5	12.0	A	
Icc	Supply current (total)		V <sub>CC</sub> = MAX	V <sub>IN</sub> = 4.5V		13.0	19.5	mA	

## NOTES:

1991 Jun 26

<sup>1.</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

All typical values are at V<sub>CC</sub> = 5V, T<sub>amb</sub> = 25°C.
Not more than one output should be shorted at a time. For testing I<sub>OS</sub>, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

Philips Semiconductors Product specification

## Quad 2-input NAND Schmitt trigger

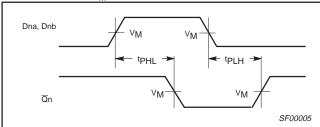
74F132

## **AC ELECTRICAL CHARACTERISTICS**

SYMBOL	PARAMETER	TEST CONDITION	Ta	/ <sub>CC</sub> = +5.0 <sub>amb</sub> = +25° 50pF, R <sub>L</sub> =	С	V <sub>CC</sub> = +5. T <sub>amb</sub> = 0°0 C <sub>L</sub> = 50pF,	UNIT	
			MIN	TYP	MAX	MIN	MAX	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay Dna, Dnb to Qn	Waveform 1	3.5 4.5	5.5 6.0	7.0 8.5	3.0 4.5	8.5 9.0	ns

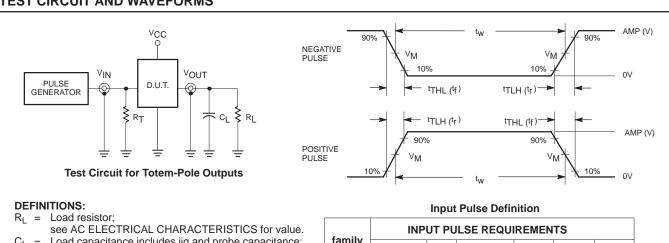
## **AC WAVEFORMS**

For all waveforms,  $V_M = 1.5V$ .



Waveform 1. For Inverting Outputs

## **TEST CIRCUIT AND WAVEFORMS**



C<sub>L</sub> = Load capacitance includes jig and probe capacitance;

see AC ELECTRICAL CHARACTERISTICS for value.

Termination resistance should be equal to Z<sub>OUT</sub> of pulse generators.

family	INP	INPUT PULSE REQUIREMENTS												
	amplitude	V <sub>M</sub>	rep. rate	t <sub>w</sub>	t <sub>TLH</sub>	t <sub>THL</sub>								
74F	3.0V 1.5V		1MHz	500ns	2.5ns	2.5ns								

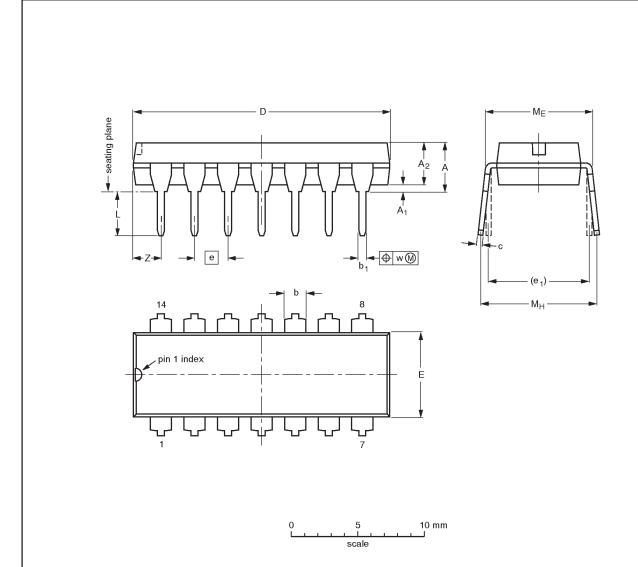
SF00006

1991 Jun 26 5

74F132

## DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1



## DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	e <sub>1</sub>	L	ME	Мн	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

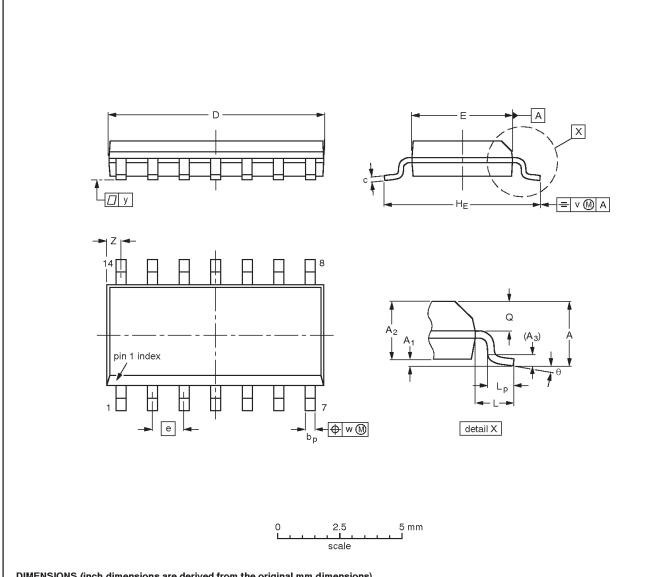
OUTLINE	OUTLINE		REFER	EUROPEAN	ISSUE DATE		
	VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	
	SOT27-1	050G04	MO-001AA			<del>92-11-17</del> 95-03-11	

1991 Jun 26 6

74F132

## SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



## DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	А3	bp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075		0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	0°

## Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN	ISSUE DATE
	IEC	JEDEC	EIAJ		PROJECTION	1990E DATE
SOT108-1	076E06S	MS-012AB				<del>95-01-23</del> 97-05-22

1991 Jun 26

74F132

#### Data sheet status

Data sheet status	Product status	Definition [1]	
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.	
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<sup>[1]</sup> Please consult the most recently issued datasheet before initiating or completing a design.

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